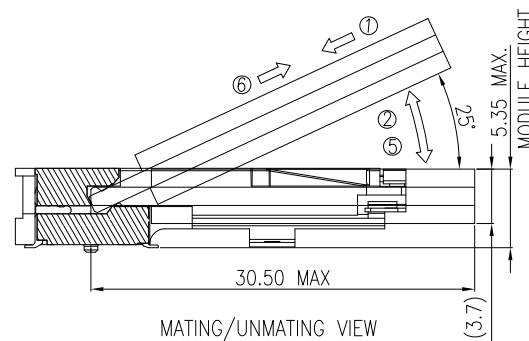
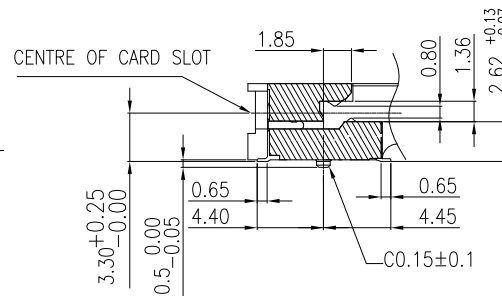
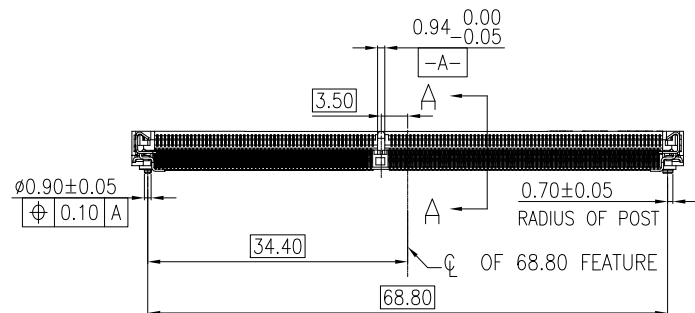
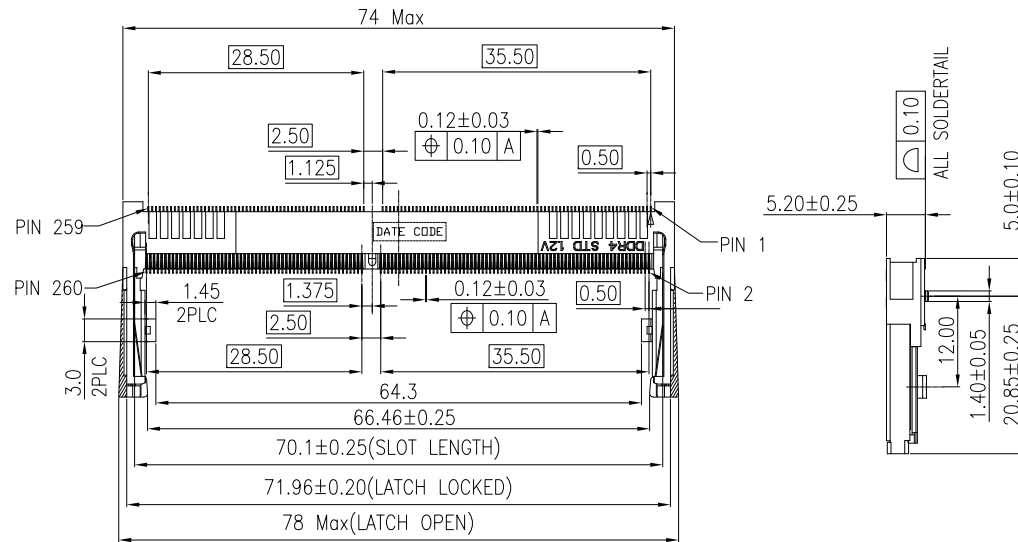


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2015/11/02	Phebe Su



MATING: ① INSERTING(30°) → ② ROTATING → ③ FIXED
UNMATING: ④ UNFIXED → ⑤ ROTATING → ⑥ WITHDRAWING

NOTES:

1.MATERIAL:

- 1.1 HOUSING:LCP,UL94V-0,COLOR:BLACK.
- 1.2 CONTACT:PHOSPHOR BRONZE.
- 1.3 SOLDER PEG AND LATCH:STAINLESS STEEL.

2. FINISH:

- 2.1 CONTACT: 50u" MIN NICKEL UNDERPLATED ALL OVER.
GOLD FALSH PLATING ON SOLDERTAIL.
GOLD PLATING (THICKNESS SEE TABLE) ON CONTACT AREA.
- 2.2 SOLDER PEG:
50u" MIN NICKEL UNDERPLATED ALL OVER.
AU 2u" MAX ON SOLDERTAIL.

3. DATE CODE : YYWWDLX

YY: YEAR (09: 2009)
WW: WEEK (25: THE 25TH WEEK)
D: DAY (1~7: SUNDAY~SATURDAY)
L: LINE NUMBER OF ASSEMBLY (A: LINE A)
X: D OR N (D: DAY; N: NIGHT)

4. PART NUMBER DESCRIPTION:

MDDR4-260X16

Series number

PLATING CODE:

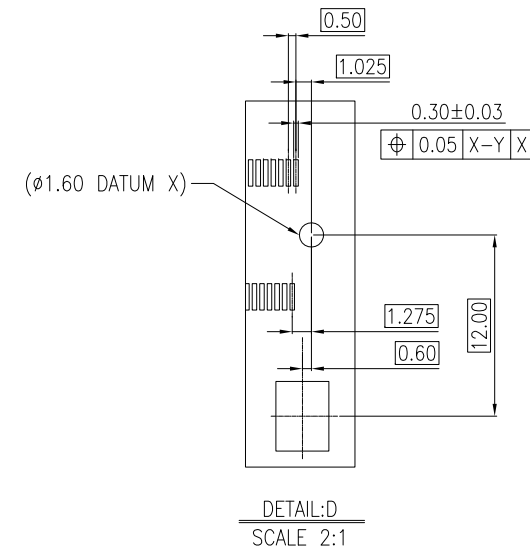
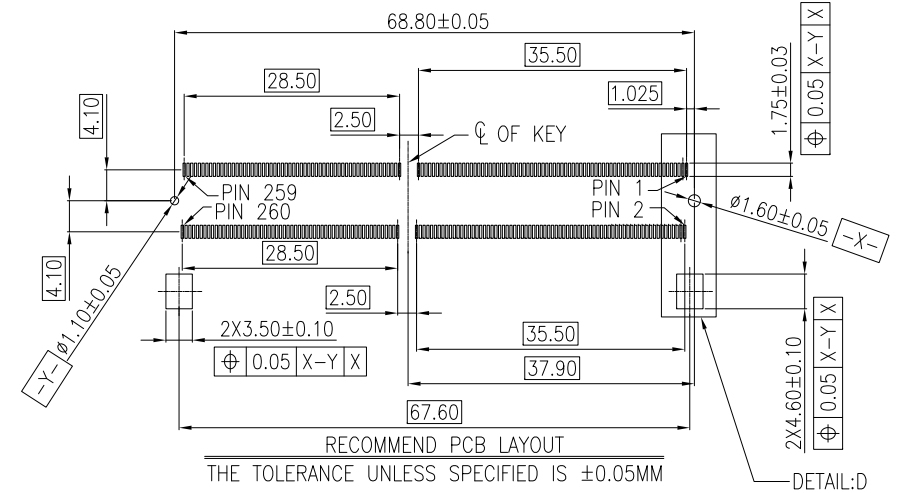
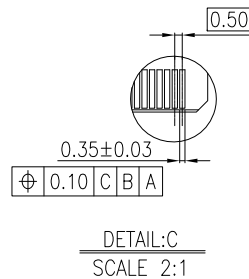
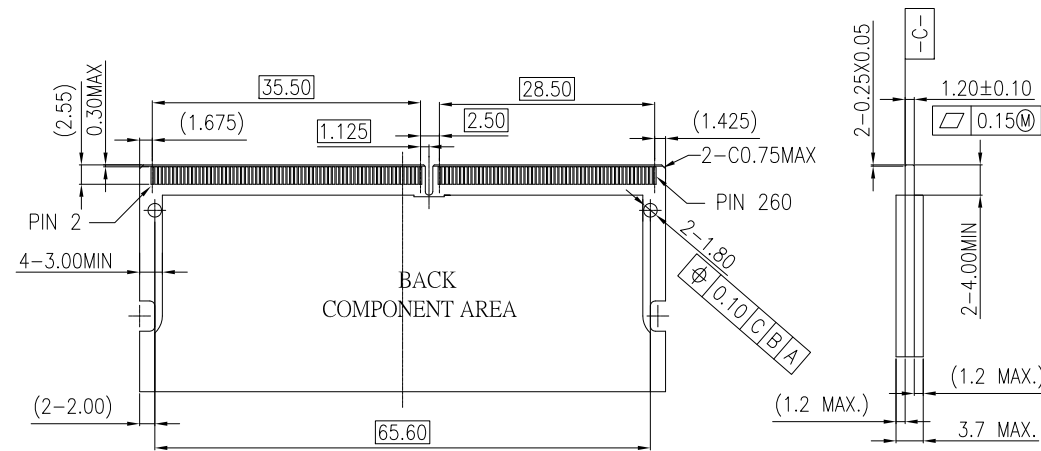
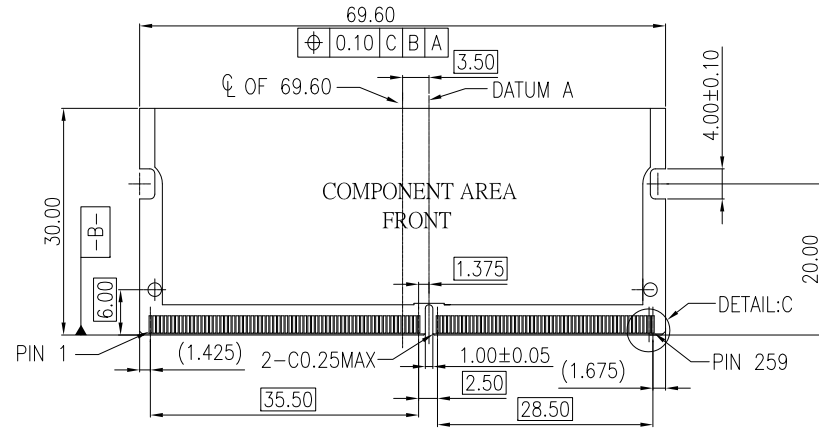
1: GF 2: Au5u" 3: Au10u"
4: Au15u" 5: Au30u"

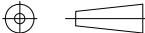
PIN NUMBER CODE: 260 PINS

NO	VARIETY	QTY	METERIAL	REMARK
 Matrix Electronics Co.,Ltd				
TOLERANCE: X:X ±0.25 X:XX ±0.15 X:XXX ±0.10 ANGLE: ±3°		DESIGN BY : Phebe Su	DATE : 2015/11/02	PART NAME: DDR4 SO DIMM 5.2H STD
CHECKED BY: Vicky Hsieh		DATE : 2015/11/02	PART NO.	MDDR4-260X16
APPROVED BY1: Richard Hsieh		DATE : 2015/11/02	MOLD NO.	NA
APPROVED BY2: Richard Hsieh		DATE : 2015/11/02	DRAW NO.	
SCALE:1:1 SIZE:A4			SHEET NO.	1 OF 2

GP Component	1
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REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2015/11/02	Phebe Su



NO	VARIETY	QTY	MATERIAL	REMARK	
 Matrix Electronics Co.,Ltd					
TOLERANCE: X: X.X ±0.25 X.XX ±0.15 X.XXX ±0.10 ANGLE: ±3°		DESIGN BY : Phebe Su	DATE : 2015/11/02	PART NAME: DDR4 SD DIMM 5.2H STD	
 UNIT: mm [inch]		CHECKED BY: Vicky Hsieh	DATE : 2015/11/02	PART NO.	MDDR4-260X16
		APPROVED BY1: Richard Hsieh	DATE : 2015/11/02	MOLD NO.	NA
		APPROVED BY2: Richard Hsieh	DATE : 2015/11/02	DRAW NO.	
SCALE:1:1	SIZE:A4			SHEET NO.	2 OF 2